



UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS  
UNITED STATES PATENT AND TRADEMARK OFFICE  
WASHINGTON, D.C. 20231  
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APPLICATION NUMBER	FILING/RECEIPT DATE	FIRST NAMED APPLICANT	ATTORNEY DOCKET NUMBER
09/690,600	10/17/2000	Peter B. Hogerton	53434USA8C/009

Office of Intellectual Property Counsel  
3M Innovative Properties Company  
P.O. Box 33427  
St. Paul, MN 55133-3427

FORMALITIES LETTER



\*OC000000005575833\*

Date Mailed: 11/27/2000



NOTICE TO FILE MISSING PARTS OF NONPROVISIONAL APPLICATION

FILED UNDER 37 CFR 1.53(b)

**Filing Date Granted**

An application number and filing date have been accorded to this application. The item(s) indicated below, however, are missing. Applicant is given TWO MONTHS from the date of this Notice within which to file all required items and pay any fees required below to avoid abandonment. Extensions of time may be obtained by filing a petition accompanied by the extension fee under the provisions of 37 CFR 1.136(a).

- The oath or declaration is missing.  
*A properly signed oath or declaration in compliance with 37 CFR 1.63, identifying the application by the above Application Number and Filing Date, is required.*
- To avoid abandonment, a late filing fee or oath or declaration surcharge as set forth in 37 CFR 1.16(e) of \$130 for a non-small entity, must be submitted with the missing items identified in this letter.
- The balance due by applicant is \$ 130.

*A copy of this notice **MUST** be returned with the reply.*

*[Handwritten signature]*

Customer Service Center

Initial Patent Examination Division (703) 308-1202

PART 2 - COPY TO BE RETURNED WITH RESPONSE

02/13/2001 BNGUYEN1 00000058 133723 09690600

02 FC:105 130.00 CH

Patent

Docket No.: 53434USA8C.009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Peter B. Hogerton, Kevin Yu Chen, Joel A.  
Gerber and Robert L. D. Zenner

Group Art Unit: 3729

Examiner:

Serial No.: 09/690,600  
Filed: October 17, 2000  
For: SOLVENT ASSISTED BURNISHING  
OF PRE-UNDERFILLED SOLDER-  
BUMPED WAFERS FOR FLIPCHIP  
BONDING



RESPONSE TO NOTICE TO FILE MISSING PARTS

Commissioner of Patents  
Washington, D.C. 20231


This is in response to the Notice to File Missing Parts of Nonprovisional Application – Filing Date Granted mailed on November 27, 2000. A copy of the Notice to File Missing Parts is enclosed.

No original declaration or oath was filed and enclosed is the original declaration for this application. The above-identified application is the application which the inventors executed by signing the enclosed declaration.

Please charge the fee provided in 37 C.F.R. §1.16(e) to Deposit Account No. 13-3723. One copy of this sheet marked DUPLICATE is also enclosed.

Respectfully submitted,

Date: 2/3/01

  
Matthew B. McNutt  
Registration No. 39,766

Office of Intellectual Property Counsel  
3M Innovative Properties Company  
P.O. Box 33427  
St. Paul, Minnesota 55133-3427  
Telephone: (512) 984-3958

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on the date below:

Date: 2-6-01

Signed: 

Tom Sanders